

Final Product/Process Change Notification Document #:FPCN25631ZA Issue Date:12 Dec 2023

Title of Change:	Qualification of IGBT Technology onsemi Bucheon 8inch Fab in Korea			
Proposed Changed Material First Ship Date:	13 Jun 2024 or earlier if approved by customer			
Current Material Last Order Date:	N/A Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged, material after this date will be per mutual agreement and current material inventory availability			
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory			
Product Category:	Active components – Discrete components			
Contact information:	Contact your local onsemi Sales Office or Susan.Du@onsemi.com			
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Sample Availability Date:	01 Mar 2024			
PPAP Availability Date:	01 Mar 2024			
Additional Reliability Data:	Contact your local onsemi Sales Office or Marco.kang@onsemi.com			
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.			
Change Category				
Category	Type of Change			
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter			
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.			

Description and Purpose:

This FPCN announces the planned IGBT fab site change to onsemi Korea 8 inch Fab from onsemi Korea 6 inch Fab. Other wafer back side processes and probes are compatible with both wafer diameters, so there is no change.

	From	То	
Fab Site	onsemi, Bucheon, Korea 6inch Fab	onsemi, Bucheon, Korea 6/8inch Fab	
Wafer size	150 mm	150mm and 200 mm	



	Reason / Motivation for Change:		Capacity improvement			
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:		successf perform	fully passed the quali	d and validated based on the sar fication tests. Potential impacts ion to the PCN, associated risks	can be identified, but o	due to testing
ites Affected:		1				
onsemi Sites				External Foundry/Subcon Sites		
onsemi Bucheon, Korea				None		
Marking of Parts/ Traceability of Changed material ca			d material can be ider	ntified by lot code.		
V DEVICE NAME	Summary: FGB20N60SFD_F085 297, K90915, S89745					
MS: K89258, O90 ACKAGE: D2PAK-	FGB20N60SFD_F085 0297, K90915, S89749 3	9				
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test	FGB20N60SFD_F085 297, K90915, S89749 3 Specificatio	9 on		Condition	Interval	Results
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test HTRB	FGB20N60SFD_F085 297, K90915, S89749 3 Specificatio JESD22-A10	9 0 n 8	Tj=150	°C, 80% rated V	1008hrs	0/77
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test HTRB HTGB	FGB20N60SFD_F085 297, K90915, S89749 3 Specificatio JESD22-A10 JESD22-A10	9 0 n 8 8	Tj=150 Ta=150°C, 1	°C, 80% rated V L00% max rated Vgss	1008hrs 1008 hrs	0/77 0/77
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test HTRB HTGB HTSL	FGB20N60SFD_F085 297, K90915, S89749 3 Specificatio JESD22-A10 JESD22-A10 JESD22-A10	9 0 n 8 8 8 3	Tj=150 Ta=150°C, 1	°C, 80% rated V LOO% max rated Vgss Ta=150°C	1008hrs	0/77
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test HTRB HTGB	FGB20N60SFD_F085 297, K90915, S89749 3 Specificatio JESD22-A10 JESD22-A10 JESD22-A10 J-STD-020 / JESD	9 8 8 3 -A113	Tj=150 Ta=150°C, 1	°C, 80% rated V L00% max rated Vgss	1008hrs 1008 hrs	0/77 0/77
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test HTRB HTGB HTSL	FGB20N60SFD_F085 297, K90915, S89749 3 Specificatio JESD22-A10 JESD22-A10 JESD22-A10	9 8 8 3 -A113 0	Tj=150 Ta=150°C, 1 MSL 1 @ 245°C, Ta=+25°	°C, 80% rated V LOO% max rated Vgss Ta=150°C	1008hrs 1008 hrs	0/77 0/77
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test HTRB HTGB HTGB PC	FGB20N60SFD_F085 297, K90915, S89749 3 Specificatio JESD22-A10 JESD22-A10 JESD22-A10 J-STD-020 / JESD MIL-STD-756 (M1037)	9 0 8 8 8 3 -A113 0	Tj=150 Ta=150°C, 1 MSL 1 @ 245°C, Ta=+25° On,	°C, 80% rated V L00% max rated Vgss Ta=150°C Surface mount pkgs only 'C, delta Tj=100°C	1008hrs 1008 hrs 1008hrs - 8572cyc	0/77 0/77 0/77 -
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test HTRB HTRB HTGB HTSL PC PC+IOL	FGB20N60SFD_F085 297, K90915, S89749 3 Specificatio JESD22-A10 JESD22-A10 JESD22-A10 J-STD-020 / JESD MIL-STD-750 (M1037) AEC-Q101	9 n 8 8 3 -A113 0 4	Tj=150 Ta=150°C, 1 MSL 1 @ 245°C, Ta=+25° On, Ta=-5	°C, 80% rated V L00% max rated Vgss Ta=150°C Surface mount pkgs only °C, delta Tj=100°C /off = 3.5min	1008hrs 1008 hrs 1008hrs -	0/77 0/77 - 0/77
V DEVICE NAME MS: K89258, O90 ACKAGE: D2PAK- Test HTRB HTGB HTGB HTSL PC PC+IOL PC+TC	FGB20N60SFD_F085 2297, K90915, S89749 3 Specificatio JESD22-A10 JESD22-A10 J-STD-020 / JESD MIL-STD-750 (M1037) AEC-Q101 JESD22-A10	9 8 8 3 -A113 0 4 0	Tj=150 Ta=150°C, 1 MSL 1 @ 245°C, Ta=+25° On, Ta=-5 130°C, 855	°C, 80% rated V L00% max rated Vgss Ta=150°C Surface mount pkgs only 'C, delta Tj=100°C /off = 3.5min 55°C to +150°C	1008hrs 1008 hrs 1008hrs - 8572cyc 1000cyc	0/77 0/77 - 0/77 0/77 0/77

Refer to the attached AEC1 Pager for more details.

To view attachments:

1. Download pdf copy of the PCN to your computer

2. Open the downloaded pdf copy of the PCN

3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment

field

4. Then click on the attached file.

Electrical Characteristics Summary:

Electrical characteristics are not impacted.



List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
FGB20N60SFD-F085	NA	FGB20N60SFD-F085
FGH40N60SMD-F085	NA	FGB20N60SFD-F086